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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/772,311 Group Art Unit: 1732
Filing Date: February 6, 2004 Examiner: Lee, Edmund H.
Applicant: Sang-Hyeop LEE et al.
Title: MOLDING METHOD AND MOLD FOR
ENCAPSULATING BOTH SIDES OF PCB MODULE
WITH WAFER LEVEL PACKAGE MOUNTED PCB

Attorney Docket: 2557-000220/US

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Randolph Building
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June 16, 2009

AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

In response to the Final Office Action mailed April 16, 2009, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Claims begin on page 2 of this Amendment.

Remarks begin on page 6 of this Amendment.

	Claims remaining after Amendment		Highest number previously paid for		Present extra
Total	9	-	20	=	0
Independent	2	-	3	=	0